ABSOCIATION CONNECTING ELECTRONICS INDUSTRIES® MAterial Comp © Copyright 2005. 1 international and Par	PC, Bannock	burn, Illinois. A	All rights reserved untions.	inder both	This docume level parts, t	ent is a declar the declaratio	ration of n encom	the substance the substance passes all low	s within th er level m	ne manufactu aterials for v	urer listed it which the m	em. Not anufacti	te: if the item is urer has engined	an assembly with lovering responsibility.		
	IPC Web Site for Information on IPC-1752 Standard Form Ty: http://www.ipc.org/IPC-175x Distribut				e *	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					rials and M	ials and Mfg Information				
Supplier Information																
Company name*	Company unique ID			Unique ID Authority					Respons	Response Date*						
onsemi										2024-05-20						
Contact Name Tit			Title - Contact			Phone - Contact*					Email -	Email - Contact*				
Product-Env-Stewards	Product Enviro Compliance				NA					Product	Product-Env-Stewards@onsemi.com					
uthorized Representative*	Title - Repre	Title - Representative			Phone - Representative*				Email - Representative*							
Product-Env-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com							
Requester Item Number	Mfr Iten	n Number				Effective Date Version Manufacturing Site 2024-05-20 TH6		turing Site	١	Veight*	UOM	Unit Type				
	FAN215	SV04EMPX						TH6		e	8.845	mg	Each			
Aanufacturing Proccess Informa	tion		,										I			
Terminal Plating / Grid Array Ma	aterial	Terminal Base	Alloy	J-STD-020 MSL Ratin		Peak Process Body Tem		ody Temperat	rature Max Time at Peak		k Temperat	Cemperature Number of Reflow Cycles		w Cycles		
Precious metal (e.g. Ag,Au, NiPdAu) (no Sn)		CU Alloy 1		1		260		C	30		secon	is 3				
comments																
evel 1 - maximum time at peak temperatu	ire during so	ldering is 10-3	0 seconds													
or more information regarding material	composition	please refer to	page 3													

RoHS Material Composition Declaration				Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	(Pb), Mercury (Hg), Hexavalent Chror	IS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead , Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl alate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe v others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and co for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of							
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	on above	Supplier Acceptance	* Accepted								
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.												
Exemption List Version	EL-2011/534/EU											
Declaration Signature												
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.												
Supplier Digital Signature Ra	stislav Drska	Le										

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	2.74	mg	Supplier	Silicon (Si)	7440-21-3		2.74	mg
Die Attach	0.518	mg	Supplier	Silver (Ag)	7440-22-4		0.4921	mg
			Supplier	Phenolic Resin-2	54208-63-8		0.0259	mg
Lead Frame	23.905	mg	Supplier	Zinc (Zn)	7440-66-6		0.048	mg
			Supplier	Iron (Fe)	7439-89-6		0.621	mg
			Supplier	Copper (Cu)	7440-50-8		23.2	mg
			Supplier	Phosphorus (P)	7723-14-0		0.036	mg
Mold Compound-Black	40.9	mg		Metal Hydroxide	proprietary data		1.4315	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		3.272	mg
			Supplier	Carbon Black (C)	1333-86-4		0.2045	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		32.72	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		3.272	mg
Plating	0.233	mg	Supplier	Palladium (Pd)	7440-05-3		0.021	mg
			В	Nickel (Ni)	7440-02-0		0.209	mg
			Supplier	Gold (Au)	7440-57-5		0.003	mg
Wire Bond - Au	0.296	mg	Supplier	Gold (Au)	7440-57-5		0.296	mg
Wire Bond - Cu	0.253	mg	Supplier	Palladium (Pd)	7440-05-3		0.0051	mg
			Supplier	Copper (Cu)	7440-50-8		0.2479	mg